

semiconductor packaging news

EV Group Achieves Die-to-Wafer Fusion and Hybrid Bonding Milestone – July 18, 2022

semiconductor packaging news

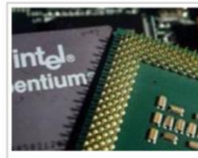
We search for industry news, so you don't need to.

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July 18, 2022

U.S. Chip Industry Split Over CHIPS Act Benefits to Intel

Several U.S. semiconductor firms are deliberating whether to oppose a package of chip industry subsidies if the final language of the legislation awaiting a vote in the Senate disproportionately benefits manufacturers like Intel, sources familiar with the matter told Reuters. Senate Majority Leader Chuck Schumer has told lawmakers that a vote could come as early as Tuesday on a slimmed-down ...
CNBC



Accelerating Heterogeneous Integration (HI)

EVG provides world-class wafer-to-wafer and die-to-wafer hybrid bonding process solutions that help customers speed the deployment of HI technologies.
EV Group



Die-Module Attach (Pastes & Films)

Die-Attach Adhesives with low moisture absorption for MSL Level-1 applications for reliability. Outstanding thermal conductivity with low moisture absorption-stress-free bonding.
AI Technology, Inc.



ASE Technology embarks on NT\$30 billion Zhongli expansion

ASE Technology Holding Co., the world's largest IC packaging and testing services provider, has begun work on a NT\$30 billion (US\$1.0 billion) expansion of its facilities ...
Focus Taiwan

New Packaging FA Solutions Using Correlated X-ray Microscopy and LaserFIB

How can you quickly find micron-sized defects in 3D devices and packages? New advances using LaserFIB and 3D X-ray microscopy enable targeted cross-section ...
Technical Paper

TSMC Trims Expansion Plans as Outlook Dims

Taiwan Semiconductor Manufacturing Company (TSMC) has pared back its plan to spend more than \$40 billion this year for capacity expansion. The outlook for demand has ...
EE Times

Technical Papers

- [Air Gap, Buried Layer and Micro-Channel Measurement](#)
- [Essential Practices for Gold Mitigation of Electronic Components](#)
- [Die-to-Wafer Bonding Key to Enabling Heterogeneous Integration](#)
- [The Journey to Full-Scale Semiconductor Packaging Manufacturing](#)
- [Dispositioning Hermetic Microelectronic Components With High Internal Moisture](#)
- [Automated Wafer TTV & Shape Metrology](#)
- [Empowering RF Front End Cellular Innovations with DSMBGA](#)

Non-Surface Approach For Device Flip

Not all wafer level packages can be sorted, picked, flipped and re-packaged using traditional vacuum tip technology. Non-surface contact handling can be effective, precise & fully automated
Royce Instruments



Pristine Surfaces with Atmospheric Plasma

Plasma cleaning options, from lab/demo units all the way to custom engineered, integrated, full-scale. [Click Here](#) to learn more.
Ontos Equipment Systems



TSMC raises sales growth forecast to 35% for 2022

Taiwan Semiconductor Manufacturing Co. (TSMC), the world's largest contract chipmaker, raised its sale growth forecast for 2022 to 35%, although some of its customers ...
Focus Taiwan

Backside Metallization

Advanced semiconductor packaging requirements for higher and faster performance continue to be the driver for mining and artificial intelligence (AI)/high performance computing (HPC) applications.
JCET



Today's Sponsor



Test Your Knowledge

What is a microelectrode?
See answer below.

NanoResolution MRS™ Sensor

Fast, Superior Inspection Performance. Increase throughput with the NanoResolution MRS™ Sensor that is 2-3x faster, delivering greater than 25 wafers (300mm) per hour. Learn more.
CyberOptics Corporation



Press Releases

Indium Corporation to Feature LED Products at MiniLED Seminar

Indium Corporation® will feature its proven, innovative products for LED manufacturing at the Mini LED Backlight Mass Production ...
Indium Corporation

EV Group Achieves Die-to-Wafer Fusion and Hybrid Bonding Milestone

EV Group (EVG) announced it has achieved a major breakthrough in die-to-wafer (D2W) fusion and hybrid bonding by successfully ...
EV Group

Global Total Semiconductor Equipment Sales On Track to Record \$118 Billion in 2022

Global sales of total semiconductor manufacturing equipment by original equipment manufacturers are forecast to reach a record ...
SEMI

STMicroelectronics Hosts French "Electronique 2030" Program Launch

STMicroelectronics hosted the President of the French Republic Emmanuel Macron, along with the Minister of the Economy, Finance and ...
STMicroelectronics

Automatic bench-top die attach system

Demonstrating MAT6200 in Booth 333 at IMAPS Boston, October 4-5, unique configuration delivering high accuracy and unmatched versatility with a user friendly PC GUI interface.
MicroAssembly Technologies



SK Hynix weighs slashing spending

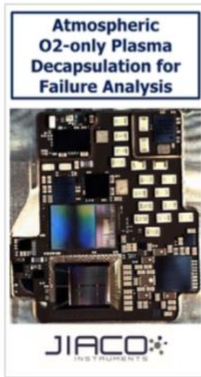
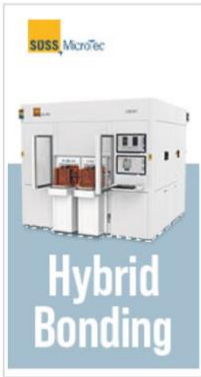
SK Hynix Inc is considering cutting its capital expenditure for next year by about one-fourth to US\$12.1 billion in response to slower electronics demand than anticipated ...

Taipei Times

Utilization rate may drop by up to 10%

Powerchip Semiconductor Manufacturing Corp said it expects its factory utilization rate to drop by as much as 10% this quarter, but is working on reallocating idled ...

Taipei Times



China firms packing more AI into their biz models

Chinese firms are using technology to innovate business models that transcend prior paradigms while setting global standards in key areas of the new economy, an ...

Asia Times

Week In Review: Manufacturing, Test

STMicroelectronics and GlobalFoundries inked a deal to build a new jointly-operated 300mm fab adjacent to ST's existing 300mm facility in Crolles, France. This facility is ...

Semiconductor Engineering

Foxconn risks fine from Taipei after taking minority stake in Chinese chip champion Tsinghua Unigroup

Foxconn Industry Internet (FII), the Shanghai-listed subsidiary of Hon Hai Technology Group, has acquired a minority stake in China's state-backed chip maker Tsinghua ...

South China Morning Post

Die Bonding Made Easy

The DL Technology X-Form needles are custom manufactured for conductive epoxy dispensing in die bonding applications. Each needle is machined using DL's patented EZ-FLO.

DL Technology



All-in-one printing of the Future

Welco® AP5112 Type 7 paste enables the single-step printing process for both flip-chip & passive component attach, which significantly reduces assembly cost and solder defects.

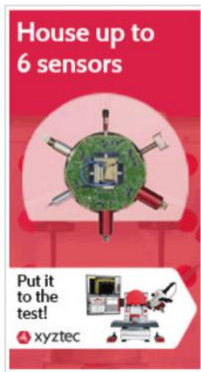
Heraeus Advanced Packaging



TSMC posts robust quarterly earnings but sees chip inventory building up at some customers amid supply chain adjustment

Taiwan Semiconductor Manufacturing Co (TSMC) said it has seen semiconductor inventory building up at some customers, with a correction in the semiconductor market ...

South China Morning Post



Quote of the Day

"That's what I consider true generosity. You give your all, and yet you always feel as if it costs you nothing."

Simone de Beauvoir

Better Bonds, with Atmospheric Plasma

Our Atmospheric Plasma systems prepare surfaces for direct bonding, remove residue, and prepare surfaces for adhesion. [Click Here](#) to learn more.



Ontos Equipment Systems

Buy Ceramic Dispensing Needles Online

Ceramic needles with Luer Lok for conductive epoxies and encapsulation. The ceramic molding process allows for smaller more precise inner diameters with a glass like finish. Buy Online.



DL Technology

What Year Was It?

FDR Nominated for Unprecedented Third Term

Franklin Delano Roosevelt is nominated for an unprecedented third term. Roosevelt would eventually be elected to a record four terms in office, the only U.S. president to serve more than two terms.



[The day was Jul 18. What year was it?](#)

Take your electronics assembly further, faster

Everything you need for



plasma surface treatment, selective soldering, fluid dispensing and conformal coating. Learn more.



Nordson ELECTRONICS SOLUTIONS

The Gold Standard of Bond Testing

Royce Instruments has been designing and building bond test equipment for over 30 years. The line of bond test equipment offers unmatched precision & robust operation for all your needs.



Royce Instruments

Cartoon of the Day



"I'm cutting back your hours from 80 a week to

Calendar

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- [Aug 22, 2022: Key Semiconductor Account Selling & Management](#)
- [Sep 19, 2022: Overview of semiconductor manufacturing/Chandler, AZ](#)
- [Sep 29, 2022: Overview of semiconductor manufacturing/Wakefield, MA](#)

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All-in-one printing of the Future

Welco® AP5112 Type 7 paste enables the single-step printing process for both flip-chip & passive component attach, which significantly reduces assembly cost and solder defects.
Heraeus Advanced Packaging



40. You get every other minute off."

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Diamond's thermal management properties enable higher performance

A collaboration between Univ. of Bristol and Element Six is accelerating diamond's path towards unlocking highly efficient thermal management solutions.



Element Six

Test Your Knowledge Answer

What is a microelectrode?

Answer: The microelectrode is a small device that electrically (or chemically) stimulates a living cell and records the electrical activity within that cell.

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